



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Huang et al.  
Serial No.: 10/720,841  
Filed: November 24, 2003  
For: Manufacture Of Carbon/Carbon Composites By Hot Pressing  
Attorney's Docket No. P2023/N9028  
Customer No. 23456

**INFORMATION DISCLOSURE STATEMENT**

Mail Stop IDS  
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Dear Sir:

Pursuant to 37 C.F.R. §1.56, applicant hereby calls to the attention of the Patent and Trademark Office the following patents and other documents which are listed on attached Form PTO-1449.

This Information Disclosure Statement is being filed before the mailing date of a first Office Action on the merits for the above-referenced application.

1. U.S. Patent No. 4,457,967 issued July 3, 1984, to Chareire et al.
2. U.S. Patent No. 4,544,412 issued October 1, 1985, to Vetri et al.
3. U.S. Patent No. 4,722,817 issued February 2, 1988, to Nakano.
4. U.S. Patent No. 5,007,508 issued April 16, 1991, to Lacombe.
5. U.S. Patent No. 5,009,823 issued April 23, 1991, to Kromrey.
6. U.S. Patent No. 5,202,293 issued April 13, 1993, to Okamoto et al.

7. U.S. Patent No. 5,246,638 issued September 21, 1993, to Goldberger.
8. U.S. Patent No. 5,256,448 issued October 26, 1993, to De Castro.
9. U.S. Patent No. 5,298,311 issued March 29, 1984, to Bentson et al.
10. U.S. Patent No. 5,306,678 issued April 26, 1994, to Yoshida et al.
11. U.S. Patent No. 5,376,595 issued December 27, 1994, to Zupancic et al.
12. U.S. Patent No. 5,377,792 issued January 3, 1995, to Idesawa.
13. U.S. Patent No. 5,439,080 issued August 8, 1995, to Haneda et al.
14. U.S. Patent No. 5,525,558 issued June 11, 1996, to Nieva et al.
15. U.S. Patent No. 5,556,704 issued September 17, 1996, to Prevorsek et al.
16. U.S. Patent No. 5,609,707 issued March 11, 1997, to Bazshushtari et al.
17. U.S. Patent No. 5,744,075 issued April 28, 1998, to Klett et al.
18. U.S. Patent No. 5,804,116 issued September 8, 1998, to Schmid et al.
19. U.S. Patent No. 5,820,788 issued October 13, 1998, to Smith.
20. U.S. Patent No. 5,876,850 issued March 2, 1999, to Skowronski et al.
21. U.S. Patent No. 5,882,570 issued March 16, 1999, to Hayward.
22. U.S. Patent No. 5,979,615 issued November 9, 1999, to Thompson et al.
23. U.S. Patent No. 5,989,504 issued November 23, 1999, to Wilson et al.
24. U.S. Patent No. 5,993,905 issued November 30, 1999, to Sheehan.
25. U.S. Patent No. 6,030,913 issued February 29, 2000, to Heine et al.
26. U.S. Patent No. 6,051,167 issued April 18, 2000, to Withers et al.
27. U.S. Patent No. 6,093,482 issued July 25, 2000, to Park et al.
28. U.S. Patent No. 6,132,877 issued October 17, 2000, to Winckler et al.

29. U.S. Patent No. 6,148,785 issued November 21, 2000, to Rivers et al.
30. U.S. Patent No. 6,183,583 issued February 6, 2001, to Duval et al.
31. SGL Carbon Company, Sigrasic Brochure, SGL Technik GmbH (May 1999) Meitingen, Germany.
32. European Patent Application 1 323 785 A2, Published on July 2, 2003, to Bauer, Moritz et al.

The Commissioner is authorized to charge any deficiency or credit any overpayment in connection with this Information Disclosure Statement to Deposit Account No. 21-0010.

Respectfully submitted,



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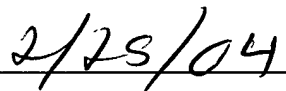
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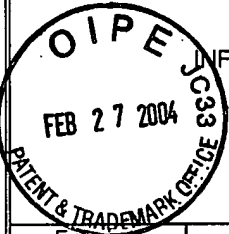
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Comparable to Form PTO-1449		U.S. Department of Commerce Patent & Trademark Office		Atty. Docket No. P2023/N9028 Customer No. 23456	Serial No. 10/720,841
 <p style="margin-top: 10px;">INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)</p>				Applicant Huang et al.	
				Filing Date 11/24/2003	Group

Examiner Initial	Document No.	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	4,457,967	July 3, 1984	Chaire et al.		
	AB	4,544,412	October 1, 1985	Vetri et al.		
	AC	4,722,817	February 2, 1988	Nakano		
	AD	5,007,508	April 16, 1991	Lacombe		
	AE	5,009,823	April 23, 1991	Kromrey		
	AF	5,202,293	April 13, 1993	Okamoto et al.		
	AG	5,246,638	Sep. 21, 1993	Goldberger		
	AH	5,256,448	October 26, 1993	De Castro		
	AI	5,298,311	March 29, 1984	Bentson et al.		
	AJ	5,306,678	April 26, 1994	Yoshida et al.		
	AK	5,376,595	Dec. 27, 1994	Zupancic et al.		
	AL	5,377,792	January 3, 1995	Idesawa		
	AM	5,439,080	August 8, 1995	Haneda et al.		
	AN	5,525,558	June 11, 1996	Nieva et al.		
	AO	5,556,704	Sep. 17, 1996	Prevorsek et al.		
	AP	5,609,707	March 11, 1997	Bazshushtari et al.		
	AQ	5,744,075	April 28, 1998	Klett et al		
	AR	5,804,116	Sep. 8, 1998	Schmid et al.		
	AS	5,820,788	Oct. 13, 1998	Smith		
	AT	5,876,850	March 2, 1999	Skowronski et al.		
	AU	5,882,570	March 16, 1999	Hayward		
	AV	5,979,615	Nov. 9, 1999	Thompson et al.		
	AW	5,989,504	Nov. 23, 1999	Wilson et al.		
	AX	5,993,905	Nov. 30, 1999	Sheehan		
	AY	6,030,913	February 29, 2000	Heine et al.		
	AZ	6,051,167	April 18, 2000	Withers et al.		
	BA	6,093,482	July 25, 2000	Park et al.		
	BB	6,132,877	October 17, 2000	Winckler et al.		
	BC	6,148,785	Nov. 21, 2000	Rivers et al.		
	BD	6,183,583	February 6, 2001	Duval et al.		
✓	EP	1 323 685 A2	July 2, 2003	Bauer et al.		

MISCELLANEOUS DOCUMENTS	
AA	SGL Carbon Company, Sigrasic Brochure, SGL Technik GmbH, (May 1999) Meitingen, Germany
Examiner:	Date Considered

\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.